

Features

- Uses BeST advanced Trench technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \cdot R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

Applications

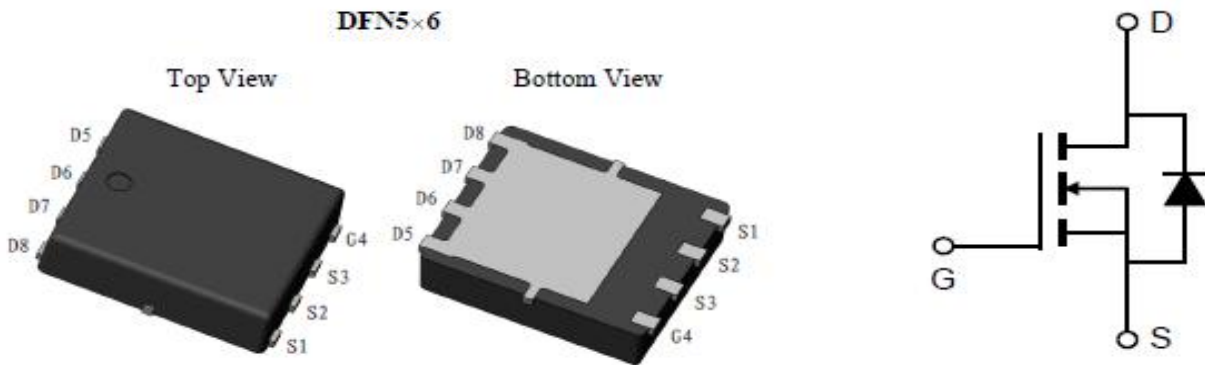
- Motor control and drive
- Battery management
- UPS

Product Summary

V_{DS}	40V
$R_{DS(on)}$ typ.	2.1mΩ
I_D	116A

100% DVDS Tested

100% Avalanche Tested



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
BST030N04ML	BST030N04ML	DFN5*6	Reel	13 Inch	N/A	5000pcs

Absolute Maximum Ratings (at $T_C = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	40	V
Continuous drain current	I_D	116	A
$T_C = 25^\circ\text{C}$ (Silicon limit)		248	
$T_C = 25^\circ\text{C}$ (Package limit)		74	
$T_C = 100^\circ\text{C}$ (Silicon limit)			
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	I_D pulse	464	A
Avalanche energy, single pulse ($L=0.5\text{mH}$, $R_g=25\Omega$)	E_{AS}	210	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	61	W
Operating junction and storage temperature	T_j, T_{stg}	-55~150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R _{thJC}	2.05	°C/W
Thermal resistance, junction – ambient(min. footprint)	R _{thJA}	47	

Electrical Characteristic (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV _{DSS}	40	-	-	V	V _{GS} =0V, I _D =250uA
Gate threshold voltage	V _{GS(th)}	1	2	3	V	V _{DS} =V _{GS} , I _D =250uA
Zero gate voltage drain current	I _{DSS}	-	0.01	1	μA	V _{DS} =36V, V _{GS} =0V T _j =25°C
		-	-	10		T _j =125°C
Gate-source leakage current	I _{GSS}	-	5	100	nA	V _{GS} =20V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	2.1	2.5	mΩ	V _{GS} =10V, I _D =50A, T _j =25°C
		-	3.7	4.5		T _j =150°C
Transconductance	g _{fs}	-	130	-	S	V _{DS} =5V, I _D =40A

Dynamic Characteristic

Input Capacitance	C _{iss}	-	5669	-	pF	V _{GS} =0V, V _{DS} =20V, f=1MHz
Output Capacitance	C _{oss}	-	686	-		
Reverse Transfer Capacitance	C _{rss}	-	318	-		
Gate Total Charge	Q _G	-	127	-	nC	V _{GS} =10V, V _{DS} =20V, I _D =40A, f=1MHz
Gate-Source charge	Q _{gs}	-	24	-		
Gate-Drain charge	Q _{gd}	-	31	-		
Turn-on delay time	t _{d(on)}	-	18	-	ns	V _{GS} =10V, V _{DD} =20V, R _{G_ext} =2.7Ω, I _D =40A,
Rise time	t _r	-	118	-		
Turn-off delay time	t _{d(off)}	-	69	-		
Fall time	t _f	-	66	-		
Gate resistance	R _G	-	1.2	-	Ω	V _{GS} =0V, V _{DS} =0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V _{SD}	-	0.8	1.3	V	V _{GS} =0V, I _{SD} =40A
Body Diode Reverse Recovery Time	t _{rr}	-	31	-	ns	I _F =40A, dI/dt=100A/μ s
Body Diode Reverse Recovery Charge	Q _{rr}	-	26	-	nC	

Typical Performance Characteristics

Fig 1: Output Characteristics

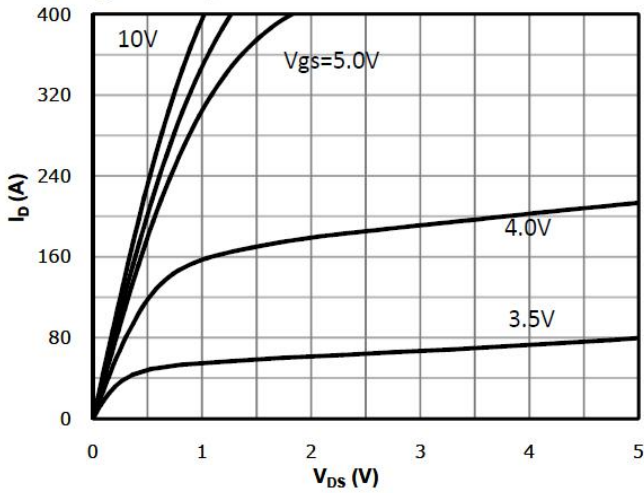


Fig 2: Transfer Characteristics

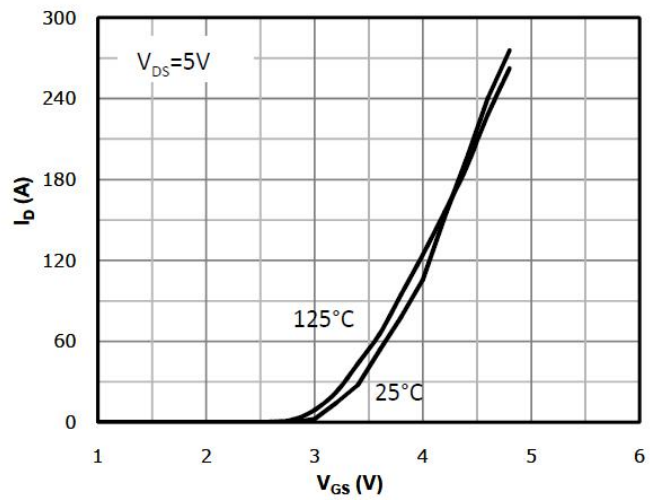


Fig 3: Rds(on) vs Drain Current and Gate Voltage

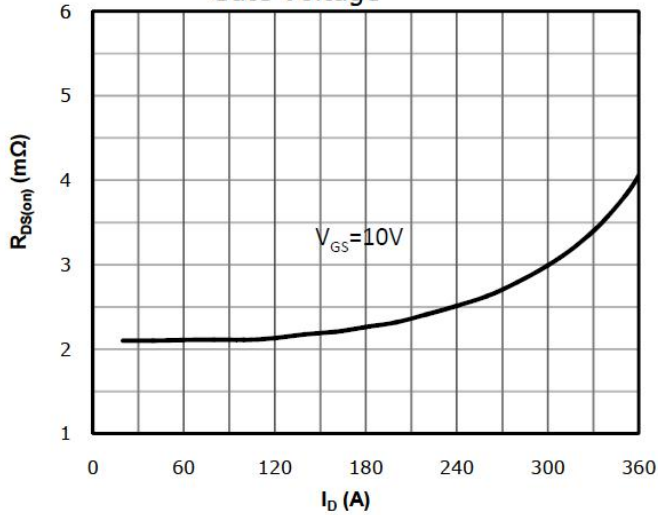


Fig 4: Rds(on) vs Gate Voltage

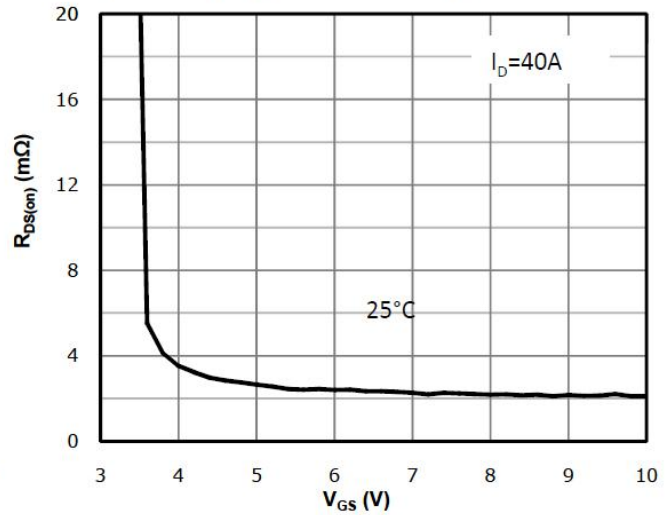


Fig 5: Rds(on) vs. Temperature

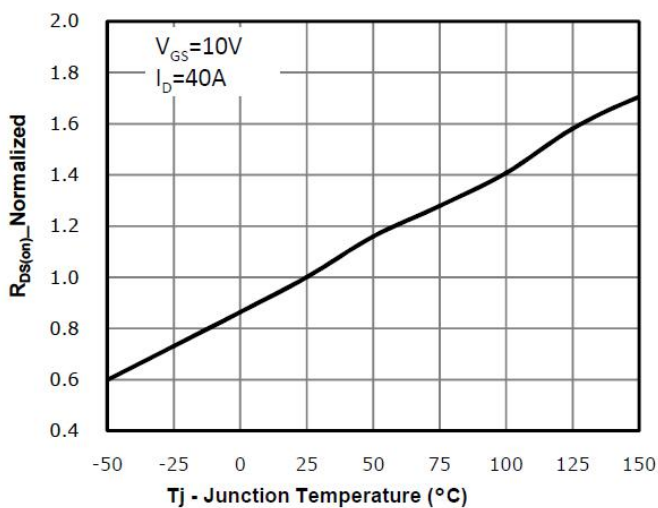


Fig 6: Capacitance Characteristics

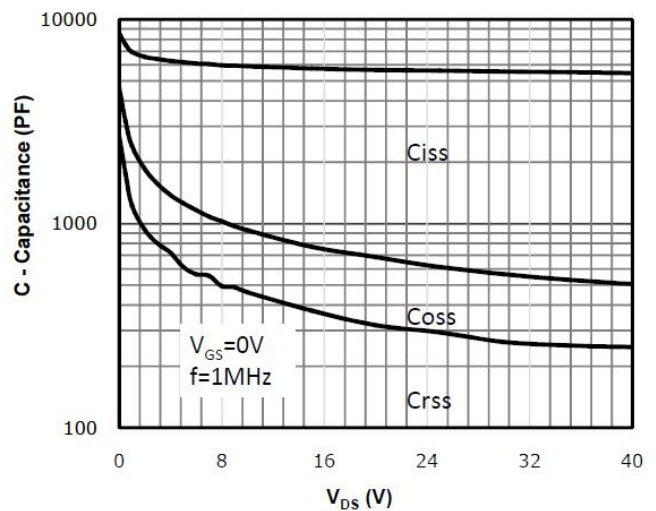


Fig 7: Gate Charge Characteristics

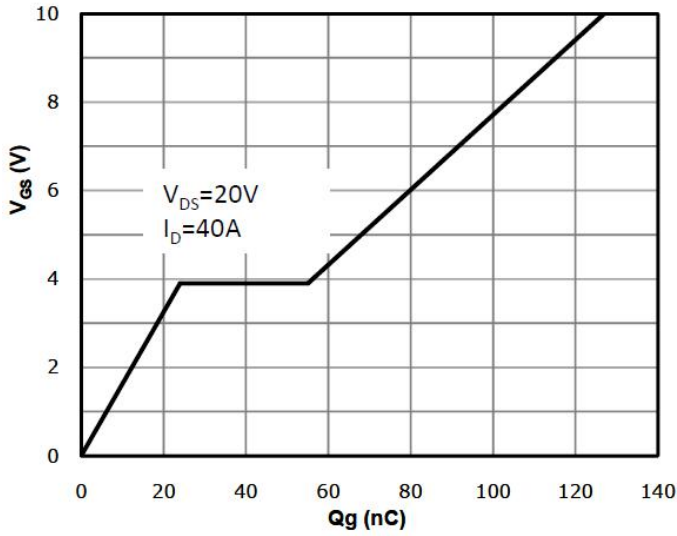


Fig 8: Body-diode Forward Characteristics

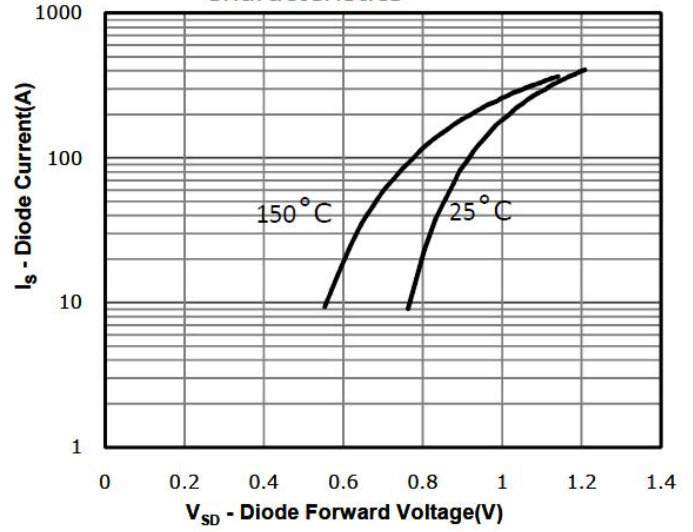


Fig 9: Power Dissipation

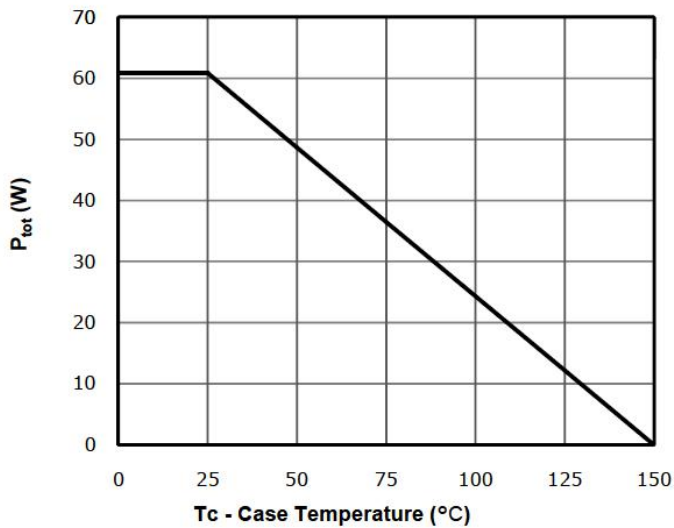


Fig 10: Drain Current Derating

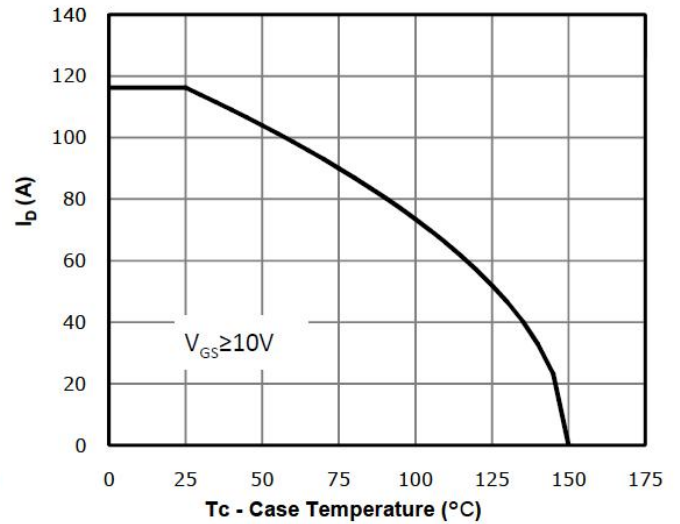
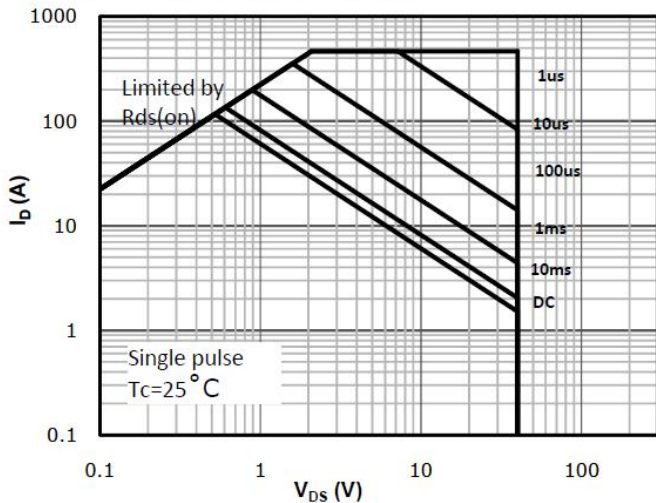
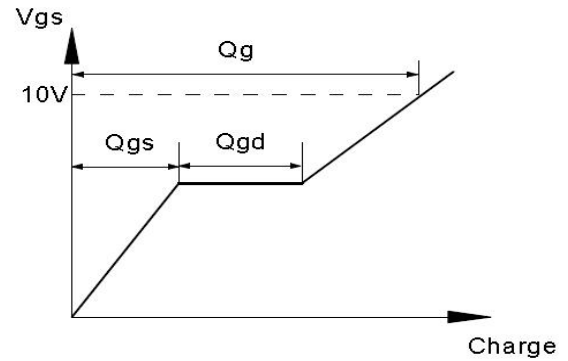
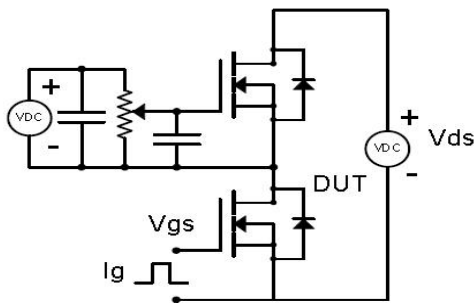


Fig 11: Safe Operating Area

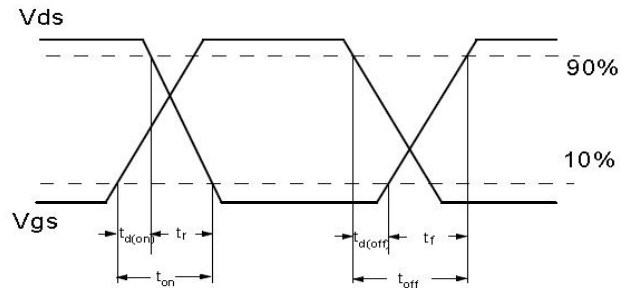
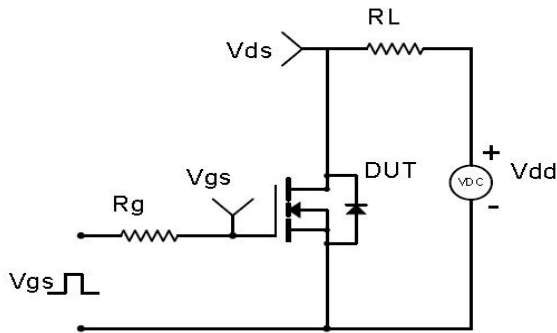


Test Circuit & Waveform

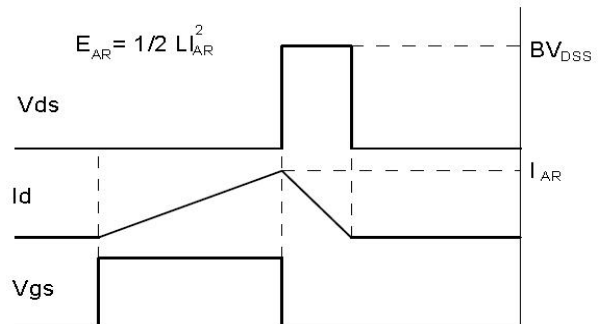
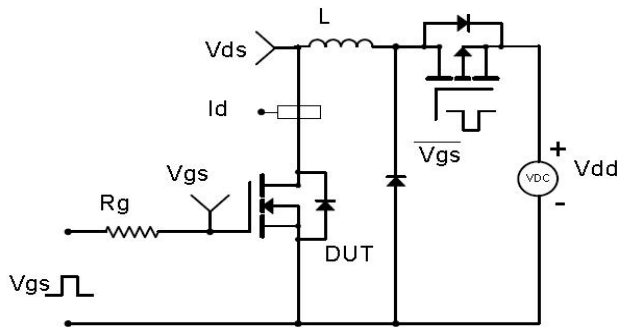
Gate Charge Test Circuit & Waveform



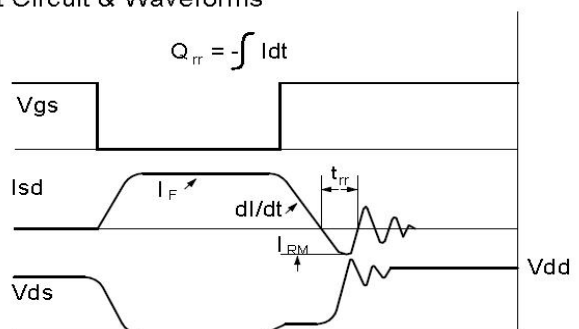
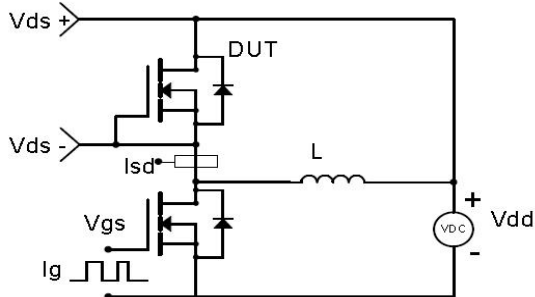
Resistive Switching Test Circuit & Waveforms



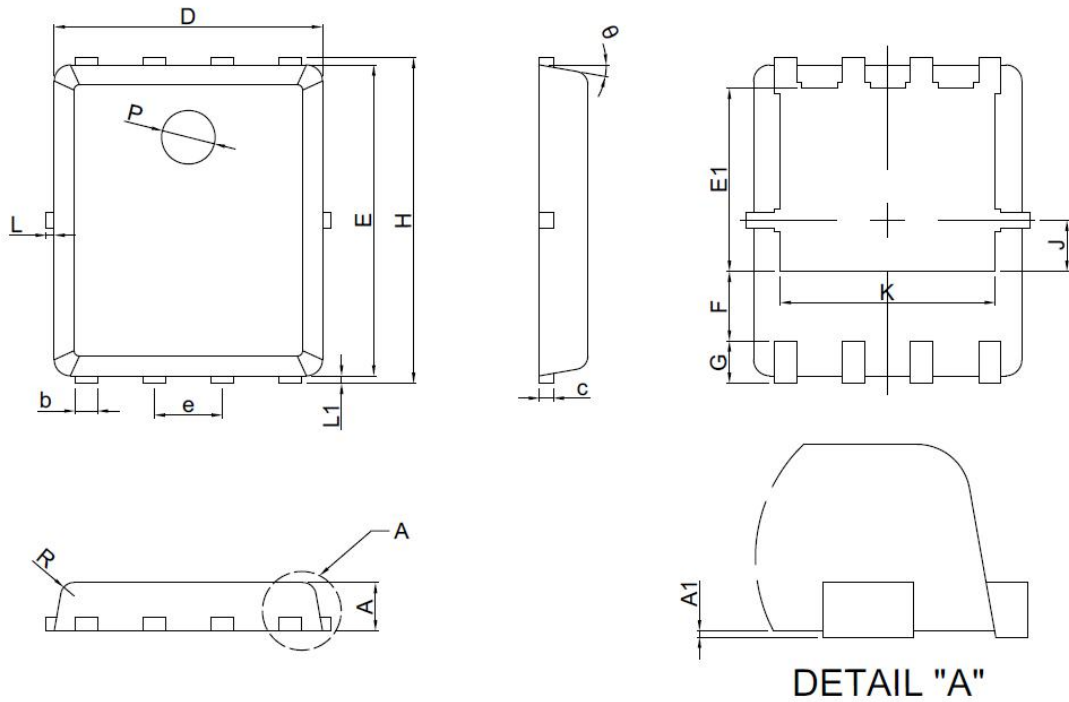
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Outline: PDFN5x6 8L



SYMBOL	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
b	0.35	0.42	0.49
c	0.254REF		
D	4.90	5.00	5.10
F	1.40REF		
E	5.70	5.80	5.90
e	1.27BSC		
H	5.95	6.08	6.20
L1	0.10	0.14	0.18
G	0.60REF		
K	4.00REF		
L	-	-	0.15
J	0.95BSC		
P	1.00REF		
E1	3.40REF		
θ	6°	10°	14°
R	0.25REF		

Revision History

Revision	Date	Major changes
1.0	2019/1/24	Release of formal version

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

BeST reserves the right to improve product design, function and reliability without notice.